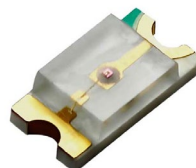




ChipLED 1206 Series
3.2*1.6*0.9mm
Single Color Package



ChipLED 1206 Red Series

A representative image

Description

- These ChipLEDs are designed in an industry-standard package.
- Various LED colors are available in seven compact, single-color packages.
- The YY1206 has the industry-standard 3.2 mm × 1.6 mm footprint, which is excellent for all-around use.
- These ChipLEDs are packaged in tape and reel with 3000 units in general per reel.
- All packages are compatible with IR reflow solder processes.
- The small size and wide viewing angle,

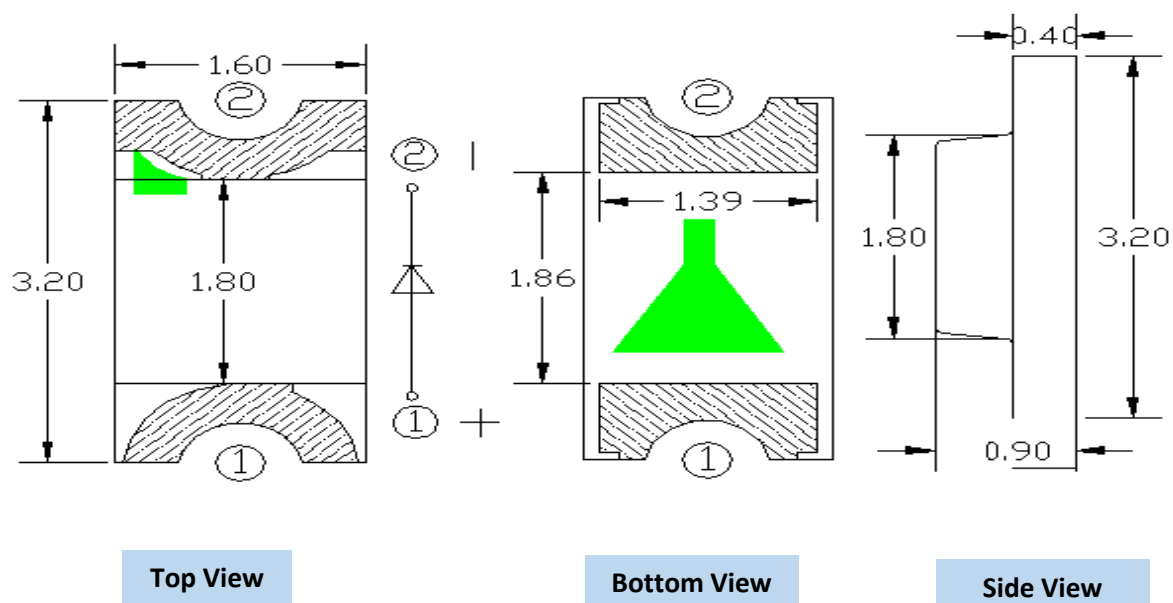
Features and Benefits

- Small size, Industry-standard footprint
- Compatible with Infrared solder process
- Compatible with automatic placement equipment
- Operating temperature range of -40°C to +85°C
- Viewing angle: 140°
- Right angle and reverse mount package available
- Various colors available
- Available in 8-mm tape, 7" reel (3000 pcs/reel), Meets EIA STD package
- Moisture sensitivity level: 3
- Halogen-free , RoHS and REACH compliant

Applications

- Keypad backlighting
- Push-button and switch backlighting
- LCD backlighting
- Symbol backlighting
- Front-panel indicator
- Optical indicator
- Home and smart appliances
- Wearable and portable devices
- Toys
- Displays for industrial control systems

Package Drawing



Note:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise specified.

Part Table

#	Part Number	Emission Color	Polarity	Zener	Binning Current (mA)	Luminous Intensity (mcd)	Dominant Wavelength (nm)	Forward Voltage (V)	Remark
1	YY1206RE-NN2S0-T5AR4	Red			10	58-175	615-630	1.8-2.4	
2	YY1206RE-NN3S0-T5AR4	Red			20	145-300	615-630	1.8-2.4	
3	YY1206RE-RN2S0-T5AR4	Red	Reverse		10	120-300	615-630	1.8-2.4	
4	YY1206RE-RN3S0-T5AR4	Red	Reverse		20	175-430	615-630	1.8-2.4	

Absolute Maximum Ratings for at Ta = 25°C

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	20	mA
Peak Forward Current(Duty 1/10 @1KHz)	I_{FP}	60	mA
Power Dissipation	P_d	48	mW
Electrostatic Discharge	ESD_{HBM}	> 2000	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec.	
		Hand Soldering : 300 °C for 3 sec.	

Luminous Intensity (Iv) Bin Limits

Bin ID	Luminous Intensity(mcd)	
	Min.	Max.
P17	58	70
P18	70	85
P19	85	100
P20	100	120
P21	120	145
P22	145	175
P23	175	210
P23-1	210	250
P24	250	300
P25	300	360
P26	360	430

Forward Voltage(V) Bin Limits

Bin ID	Forward Voltage(V)	
	Min.	Max.
VD	1.7	1.8
VE	1.8	1.9
VF	1.9	2.0
VG	2.0	2.1
VH	2.1	2.2
VI	2.2	2.3
VJ	2.3	2.4

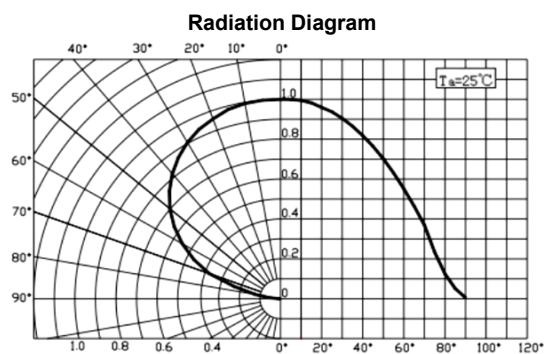
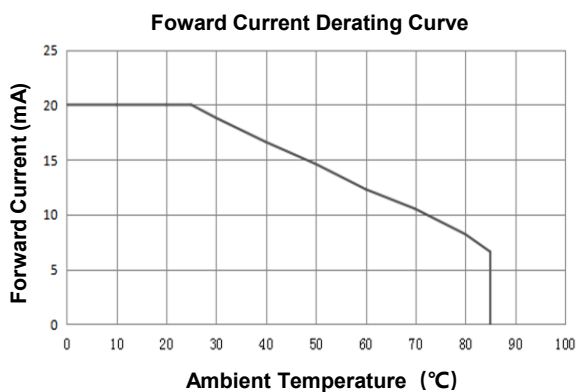
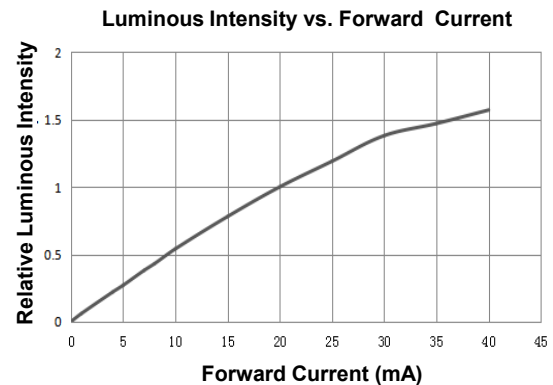
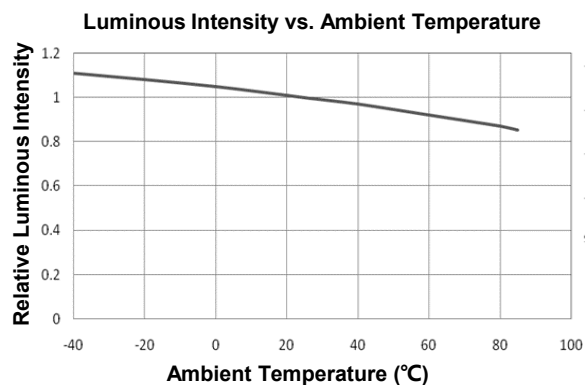
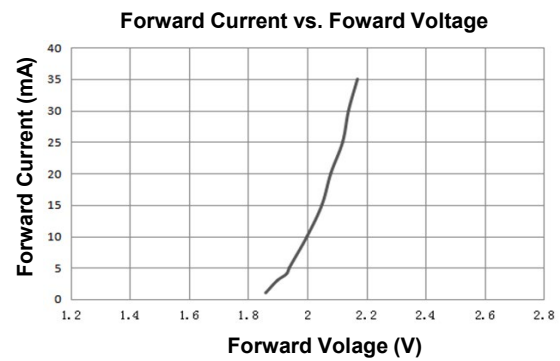
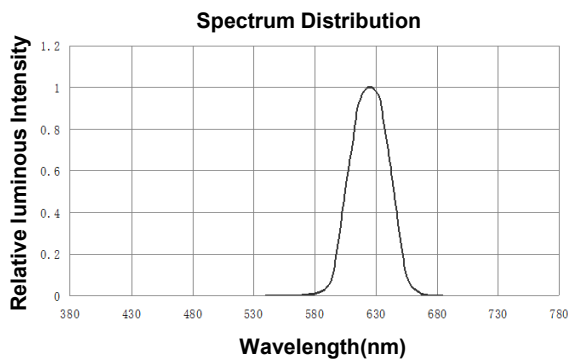
Dominant Wavelength (nm) Bin Limits

Bin ID	Dominant Wavelength (nm)	
	Min.	Max.
R1	615	618
R2	618	621
R3	621	624
R4	624	627
R5	627	630

- * Tolerance of measurement of luminous intensity is $\pm 10\%$.
- * Tolerance of measurement of dominant wavelength is ± 1 nm.
- * Tolerance of measurement of forward voltage is $\pm 0.05V$.

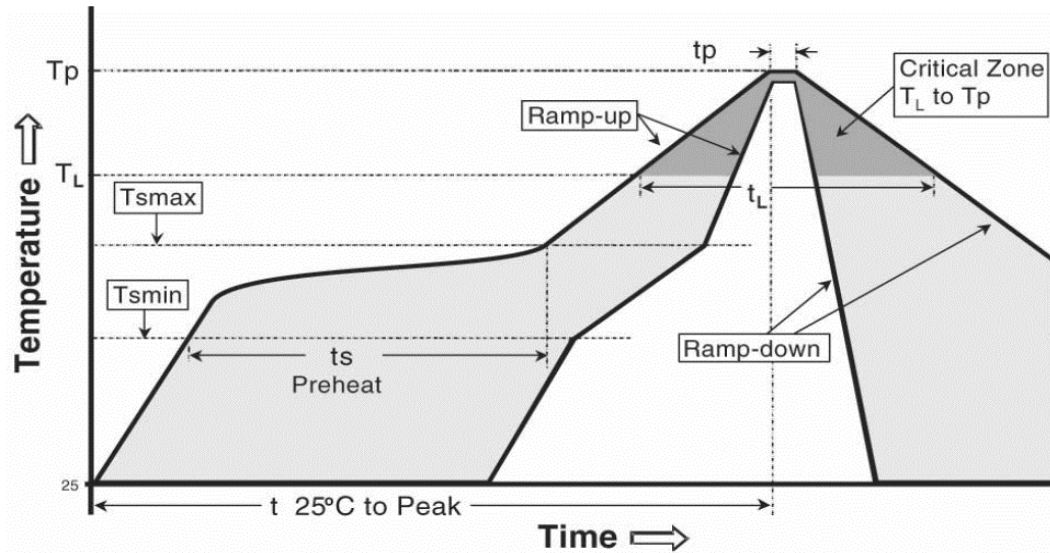
TYPICAL ELECTRO-OPTICAL CHARACTERISTICS CURES(Ta=25°C)

The data below are collected from statistical figures that do not necessarily correspond to the actual parameters of each single LED. Hence, these data will be changed without further notice.



REFLOW SOLDERING

- The ChipLED is rated as a MSL3 as general request product.
- The recommended floor life out of bag is 24hrs.
- The temperature profile is as below.



IPC/JEDEC J-STD-020C

Profile Feature	Pb-Free Assembly
Average ramp-up rate(Tsmax to Tp)	3°C/second max.
Preheat	
- Temperature Min(Tsmin)	150°C
- Temperature Max(Tsmax)	200°C
- Time(Tsmin to Tsmax)	60-180 seconds
Time maintained above	
- Temperature(T _L)	217°C
- Time(T _L)	60-150 seconds
Peak Temperature(Tp)	260°C
Time within 5°C of actual peak Temperature(tp) ²	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to peak Temperature	8 minutes max.

Moisture Sensitivity

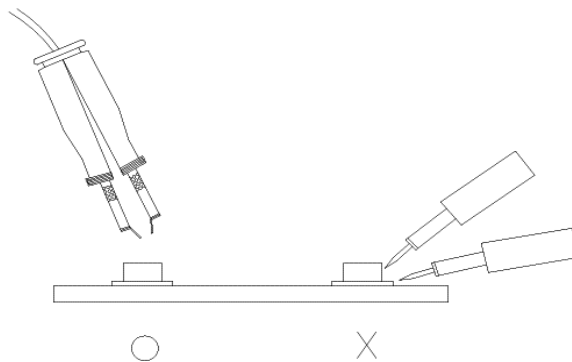
- Yongyu recommends keeping ChipLEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain ChipLEDs do not need special storage for moisture sensitivity.
- Once the MBP is opened, ChipLEDs may be stored as MSL 3 per IPC/JEDEC J-STD-020C, meaning they have one year of floor life in conditions of $\leq 30^{\circ}\text{C}/60\%$ relative humidity (RH). Regardless of the storage condition, Yongyu LED recommends sealing any unsoldered ChipLEDs in the original MBP.

Handling

- The packaging sizes of these SMD products are very small. Users are required to handle with care.
- To avoid damaging the product's surface and interior device, it is recommended to choose a special nozzle to pick up the SMD products during the process of SMT production. If handling is

Repairing

Repair should not be recommended after SMT production. When repairing is needed, a double-head soldering iron should be used (as below figure). It should be assured before handing whether the electrical and optical characteristics of the LEDs will or will not be damaged by repairing.



PACKING

- The LEDs are packed in cardboard boxes after packaging in normal or anti-electrostatic bags.
- Cardboard boxes will be used to protect the LEDs from mechanical shock during transportation.
- The boxes are not water resistant, and they must be kept away from water and moisture.
- The reel pack is applied in SMD LED.
- 3000pcs per reel.

